TEXAS INSTRUMENTS 12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN#20230816000.1
Qualification alternate mount compound material for select devices
Change Notification / Sample Request

Date: August 17, 2023
To: TOKYO ELECTRON DEVICE (DSTR) PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

Texas Instruments requires acknowledgement of receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance and approval of this change. If samples or additional data are required, requests must be received within **30 days** of this notification.

The changes discussed within this PCN will not take effect any earlier than the proposed first ship date on Page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice or to provide acknowledgement of this PCN, you may contact your local Field Sales Representative or the change management team.

For sample requests or sample related questions, contact your local Field Sales Representative.

Sincerely,

Change Management Team
SC Business Services

20230816000.1
Change Notification / Sample Request
Attachments

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, you have recently purchased these devices. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
TLV70725PDQNR	null
TLV707285DQNT	null
TLV71733PDQNR	null

Technical details of this Product Change follow on the next page(s).

PCN Number:	20230816000.1	**PCN Date:**	August 17, 2023

Title:	Qualification of alternate mount compound material for select devices

Customer Contact:	Change Management team	**Dept:**	Quality Services
Proposed 1st Ship Date:	Nov 14, 2023	**Sample Requests accepted until:**	Sept 16, 2023*

***Sample requests received after Sept 16, 2023 will not be supported.**

Change Type:

☐	Assembly Site	☐	Design	☐	Wafer Bump Material
☐	Assembly Process	☐	Data Sheet	☐	Wafer Bump Process
☒	Assembly Materials	☐	Part number change	☐	Wafer Fab Site
☐	Mechanical Specification	☐	Test Site	☐	Wafer Fab Material
☐	Packing/Shipping/Labeling	☐	Test Process	☐	Wafer Fab Process

PCN Details

Description of Change:

This PCN is to inform of an alternate mound compound material set for the list of devices in the product affected sections below.

What	Current	Additional
Die attach material	**4224819/4223872**	**4221460 + 4226215**

Reason for Change:

Standardization

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None

Impact on Environmental Ratings

Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.

RoHS	REACH	Green Status	IEC 62474
☒ No Change	☒ No Change	☒ No Change	☒ No Change

Changes to product identification resulting from this PCN:

None

Product Affected:

SN1205066PDQNR	TLV70727PDQNR	TLV70736PDQNT	TLV71729PDQNT
SN1206013PDQNR	TLV70727PDQNT	TLV717185PDQNR	TLV71733PDQNR
TLV70712PDQNR	TLV707285DQNR	TLV717185PDQNT	TLV71733PDQNT
TLV70712PDQNT	TLV707285DQNT	TLV71718PDQNR	TLV74010PDQNR
TLV70718PDQNT	TLV707285PDQNR	TLV71718PDQNT	TLV74012PDQNR

TLV70719PDQNR	TLV707285PDQNT	TLV71727PDQNR	TLV74018PDQNR
TLV70719PDQNT	TLV70732DQNR	TLV71727PDQNT	TLV74028PDQNR
TLV70725PDQNR	TLV70732DQNT	TLV71729PDQNR	TLV74033PDQNR
TLV70725PDQNT			

TI Information
Selective Disclosure

Qualification Report

xQFN Offload Into CDAT - DQN (CMOS9T5V)
Approve Date 25-April-2023

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: LP5907SNX-3.0/NOPB	QBS Reference: TLV70732DQNR	QBS Reference: LP8556TMX-E09/S1
HAST	A2	Biased HAST	110C/85%RH	264 Hours	-	-	-
UHAST	A3	Autoclave	121C/15psig	96 Hours	-	-	-
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	3/231/0	-	-
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	3/231/0	-	-
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	-	-
HTSL	A6	High Temperature Storage Life	170C	420 Hours	3/231/0	-	-
HTOL	B1	Life Test	125C	1000 Hours	-	-	3/231/0
ELFR	B2	Early Life Failure Rate	125C	48 Hours	-	-	3/915/0
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes); PB-Free Solder;	-	-	1/22/0	-
PD	C4	Physical Dimensions	(per mechanical drawing)	-	3/15/0	-	-
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	1/30/0	-	-

- QBS: Qual By Similarity

- Qual Device LP5907SNX-3.0/NOPB is qualified at MSL1 260C

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

TI Qualification ID: R-CHG-2111-019

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.

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